Standardized I	Information for Process/Product Ci	hange Notification	(PCN)	4 2011							
	1. PCN basic data DIGI-KEY CORPORATION DIGI-KEY CORPORATION										
Customer		ontact Email address: DigiKey.SupplierInfo@digikey.com, William.Walsh@digike					lsh@digikey.com				
	Customer										
			Site submitting the change:		Melexis leper						
	AAalavia										
	Melexis			Melexis							
	INSPIRED ENGINEERING		Affected site(s):	Supplier	Melexis leper	Melexis Erfurt	Melexis Sofia				
1.1 Company 1.2 PCN No.			MCM-5707	L							
1.3 Title of PC	CN CN			MCM-5707 Business Continuity Plan Unisem Batam Products							
1.4 Product Ca			Active Components - Integrated Circuits								
1.5 Issue date 1.6 PCN revision			16-07-19 1.7 Issue date of previous revision	16-07-19 1.7 Issue date of previous revision 1.8 Delta to previous revision (optional)							
V1.0	on instant (optional)		15-07-19	Initial PCN							
V2.0 V3.0			29-08-19	Initial PCN updat	te ucts in UA GR CAP						
V3.0			10-00-20	Illiai FCN - proud	ICIS III OA GN CAF						
				2. PCN Te	eam						
2.1 Contact su	upplier		1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1								
2.1.1 Name 2.1.2 Phone			con_mlx (Lisa Vanheerswynghels) +32 57 22 62 07								
2.1.3 Email			pcn_mlx@melexis.com								
	plier (optional)				1						
2.2.1 Name (o	sCustomer Communication Coordination	ation	2.2.2 Phone (optional)		2.2.3 Email (optional) hth@melexis.com						
Vincent Vanzer	verenGlobal Quality Manager	10011			vvn@melexis.com						
Karen Stincker	nsGlobal Purchasing Manager Package Architect		+		kss@melexis.com tmv@melexis.com						
Arnaud Devosl	Functional Safety and Reliability Mar	nager			ade@melexis.com						
No.	3.0 Ident		3.1 Category	3. Chang	3.2 Type of change						
#1	SEM-PA-18		PROCESS - ASSEMBLY		Move of all or part of assembly t	o a different location/site/s	ubcontractor				
#2	SEM-PA-07		PROCESS - ASSEMBLY		Die attach material						
#3	SEM-PA-16		PROCESS - ASSEMBLY		Change of direct material suppli						
#4	SEM-PA-17 SEM-PA-19		PROCESS - ASSEMBLY PROCESS - ASSEMBLY		Change of specified-assembly p Die Scribe or separation	rocess sequence (deletion	n and/or additional proces	is step)			
#5 #6	SEM-EQ-02		EQUIPMENT			nt/tool which uses the san	ne basic technology (repla	acement equipment or extension of			
					existing equipment pool) without	change of process.	37 (1				
		Old		4. Description	of change New						
Change #1			e location : Unisem Batam (Indonesia)		Assembly house location : See	section 11.					
Change #2		topic is subject o	of the capacitor attach material only:		topic is subject of the capacitor						
Change #2		F541 HBF-HBCDD free			M705-RGS800HF No Clean (SAC305)						
Change #3		capacitor attach	supplier: Heraeus		capacitor attach supplier: SMI						
		gold wire supplie			gold wire supplier: Tanaka						
Change #4		Process sequen	ce Unisem : k / Trim / Singulation		Process sequence Lingsen : Dejunk / Trim -> Plating -> Sing	ulation					
Change #5		die sawing metho	The state of the s								
Change #6		die sawing metri	ou. Olligio		sawing, plasma cleaning, molding						
	diment of four fit fourth	- Based on Rick	Accessment including AEC_O100 and 7V/E	Sawing, plastic dealing, moding							
	ed impact on form, fit, function, processability?	- Use of package	ssessment including AEC-Q100 and ZVEI guidelines eneric qualification data (from the assembly houses and Melexis) considering Automotive Grades, Assembly Bill-of-Material & Bill-of-Process and Wafer Technology								
,	,	- Whenever poss	sible, re-use of Melexis qualified Bill-of-Mate	, re-use of Melexis qualified Bill-of-Material & Bill-of-Process will be applied							
4.7 Reference	parts with customer number										
				Reason / motivat		0.0.0040					
5.1 Motivation 5.2 Additional explanation (optional)			Discontinuation communication from Unisem about operations closure at Unisem Batam by 30-Sep-2019. On 28-Jun-2019 Melexis received formal notification about Unisem Batam' Operations discontinuation (see Melexis letter dated 01-Jul-2019).								
5.2 Additional explanation (optional)		Melexis is using Unisem Batam as subcontractor for the assembly of several products.									
		Subsequently, Melexis has decided to execute its Business Continuity Plan and activate alternative sources to the fullest extent.									
			6. Mari	king of parts / tra	ceability of change						
6.1 Description	in .		Traceability through lot number and shipn								
7.1 Data of			a cailable	7. Timing / so	chedule						
	ualification results date (optional)		available Closed	 							
	ery date (optional)		Q4 2019								
7.4 Intended s	start of delivery		Q2 2020								
7.5 Qualificati	ion samples available?		Yes available								
7.6 Customer	feedback required until		30-Jun-2020								
				0.0	/lid-4i						
8 1 Description	on (e.g. qual. plan/report, AEC-Q)	1	- Based on Risk Assessment including A	8. Qualification / EC-Q100 and ZVE							
0.1 Descriptio	in (e.g. quai. plan) report, Acc-Q	- Use of package generic qualification data (from the assembly houses and Melexis) considering Automotive Grades, Assembly Bill-of-Material & Bill-of-Process and Wafer Technology									
			- Whenever possible, re-use of Melexis q	ualified Bill-of-Mat	erial & Bill-of-Process will be appli	ed					
8.2 Qualification report and qualification results available (see attachment) issue date											
			9. Input to	customer for ris	k assessment process						
See attached presentation: BOM & BOP Risk Assessment											
1											
1											
1											
L											
			10. Attachments (e.g. new datasheet,	additional docum	nentation, pictures, process flov	v, sample plan,)					
	Risk Assessment UA with Cap_Final										
INITYA 55551 W	ILX92241_MLX92242_UA_cap_Proc	uct_Qualification	_report.par								

11. Affected parts									
				11.2 New (if applicable)					
11.1.1 Customer		11.1.3	11.1.4 Package	Part Description	Additional Part Information		11.2.3		11.2.6 Additional Part
Part No.	11.1.2 Supplier Part Name	Assembly House	Name	(optional)	(optional)	11.2.2 Supplier Part Name	Assembly House	11.2.4 Package Name	Information (optional)
N/A	MLX92242LUA-AAA-100-BU	Unisem Batam	UA GR CAP			MLX92242LUA-AAA-100-BU	Lingsen, Taiwan	UA GR CAP	
N/A	MLX92242LUA AAA 100 BU	Unisem Batam	UA GR CAP			MLX92242LUA AAL 100 BU	Lingsen, Taiwan	UA GR CAP	- was for intermediate solution only - the PCN does not cover and support the intermediate solution anymore - the intermediate solution go to End

Customer Feedback/Ap	proval Form	Title of PCN:						
	Business Conti	nuity Plan Unisem E	Satam Products					
Customer PCN No.		Suppl	Supplier PCN No. MC					
Please check the appro	priate box below:							
1. Feedback		date:						
	his proposed change for the p will be sent in written form.	oarts as listed in ch	apter '11. Affected	parts'.				
	We agree with this proposed change schedule and will start with the PCN process. Approval letter will be sent in written form after evaluation.							
We disapprove	We disapprove because:							
Remark:	Remark:							
2. Feedback		date:						
	e qualification / validation as a	-	er 8 of the PCN.					
We need more in								
we need more ii	ntormation:							
We need the following	We need the following samples:							
Estimate de la che	and determined							
Estimated closis	ng date for PCN:							
Final Feedback	k/Annroval	date:						
i mai i ccasaci	MADDIOVAI	uuto.	_					
Company:		Sender:						
Name:								
Address/Location:								
Signature:								
Date:	-							
Please return to: [your Sales partner] Name: pcn_mlx (Lisa Vanheerswynghels)								
Address/Location: pcii_mix (clsa varineerswyrighers)								
Phone: Fax:	+32 57 22 62 07							
ı un.								